

In the Specification:

Please replace the paragraph beginning on page 5, line 11, of the specification with the following rewritten paragraph.

In an exemplary embodiment of the invention, the substrate may be formed by a DCB (direct copper bonding) substrate. A DCB substrate of this kind should be understood to be a ~~ceramics~~ ceramic substrate which is coated on two sides with copper and is directly mounted on the semiconductor components. Advantages of DCB substrates include: good mechanical stability, corrosion resistance and excellent electrical insulation combined with a very good thermal conductivity. DCB substrates exhibit good stability as regards thermal alternating cycles and, furthermore, have a thermal expansion coefficient which approaches that of silicon, so that no intermediate layers to the semiconductor component are required in order to compensate for differences in thermal expansion. Finally, structuring and processing are very simple.

Please replace the paragraph beginning on page 15, line 1, of the specification with the following rewritten paragraph.

Figure 1 shows an exploded sectional view of an integrated circuit system 100 according to an exemplary embodiment of the present invention. The modular structure shown here comprises the integrated circuit 102, the latent heat storage module 104, and a cooling body 106. Here, the integrated circuit 102 has a plurality of semiconductor components 108 which are assembled on a substrate 110. In the present case, the substrate 110 is formed by a so-called DCB substrate (direct copper bonding), where copper layers 114, 116 are applied onto both sides of a ~~ceramics~~ ceramic layer 112. A plastic housing shell 118 protectively covers the

semiconductor components 108, and allows assembly of the integrated circuit 102 on the latent heat storage module 104 via the screws 120. The latent heat storage module 104 is formed by a latent heat storage housing 122 which contains the actual latent heat storage medium 124.

Please replace the paragraph beginning on page 26, line 13, of the specification with the following rewritten paragraph.

The highly-integrated solution shown in Figs. 28 and 29 has the advantage that expensive power substrates are no longer required. Furthermore, the thermal resistance of the insulating substrate, which is a ~~ceramics~~ ceramic layer in the embodiments with the DCB substrate, is avoided. Especially in applications which deliver only a short-duration but nevertheless very high power dissipation in particular, significantly higher peak loads may thus be permitted. Furthermore, because joining techniques such as soldering on a copper plate are not required, this embodiment may offer a high load and thermal fatigue resistance. Thus, this embodiment may be advantageously used for soft-start devices to induce electric motors, frequency converters for highly dynamic servomotors in drive technology as well as for starter generator converters in the automobile industry.